



PATENT ABSTRACTS OF JAPAN

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(21) Application number: **11267008**(22) Date of filing: **21.09.99**(71) Applicant: **SUMITOMO BAKELITE CO LTD**(72) Inventor: **SAKAMOTO YUJI****(54) METHOD FOR ASSEMBLING SEMICONDUCTOR DEVICE****(57) Abstract:**

PROBLEM TO BE SOLVED: To provide a method for assembling a semiconductor device by which a manufacturing step can be shortened greatly and is excellent in reliability.

SOLUTION: This method for assembling a semiconductor device includes a step 1 for applying a thermosetting liquid sealing resin composition to a wafer wherein the number of semiconductor elements having solder bumps for electric

connection are formed, a step 2 for making the thermosetting liquid sealing resin composition to be tack-free, a step 3 for dicing the wafer into individual semiconductor elements, and a step 4 for electrically joining the separated semiconductor elements with a substrate provided with electric wirings, heating/fluidizing the thermosetting liquid sealing resin composition, and cooling it and press-fitting them. In this case, the thermosetting liquid sealing resin composition contains an epoxy resin of two functions or more, a curing agent having a flux work, and a curing promoter.

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